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(12) **United States Design Patent**
Alfaro et al.

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(54) **CERAMIC BONDING TOOL WITH TEXTURED TIP**

(71) Applicant: **COORSTEK, INC.**, Golden, CO (US)

(72) Inventors: **Cesar Alfaro**, Lewisville, TX (US); **Russell Bell**, Ventura, CA (US); **Anne Cenedella**, Evergreen, CO (US); **Steve Govorchin**, Superior, CO (US); **Mark S. Greenwell**, Ventura, CA (US); **Brian Seegmiller**, Arvada, CO (US); **Matthew Simpson**, Evergreen, CO (US)

(73) Assignee: **CoorsTek, Inc.**, Golden, CO (US)

(**) Term: **15 Years**

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Related U.S. Application Data

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(51) **LOC (11) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/144**

(58) **Field of Classification Search**
USPC D8/29.1, 29.2, 30; D13/123, 133;
D15/122, 138, 144, 144.1, 144.2
(Continued)

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Primary Examiner — Patricia A Palasik

(74) *Attorney, Agent, or Firm* — Faegre Baker Daniels LLP

(57) **CLAIM**

The ornamental design for a ceramic bonding tool with textured tip, as shown and described.

DESCRIPTION

FIG. 1 depicts a perspective view of a ceramic bonding tool with textured tip.

FIG. 2 depicts a side elevation view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 3 depicts a top plan view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 4 depicts a bottom plan view of the ceramic bonding tool with textured tip of FIG. 1.

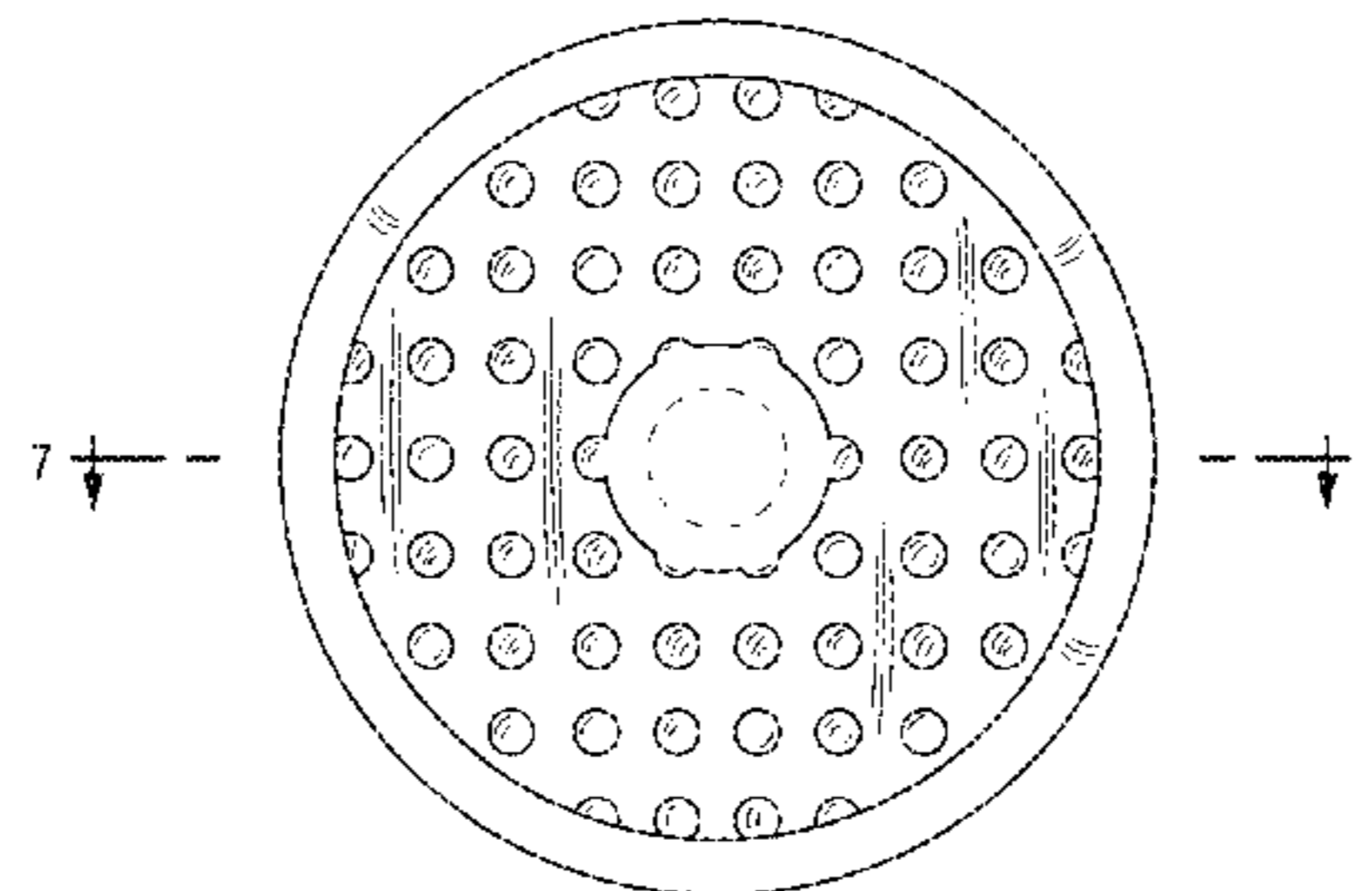
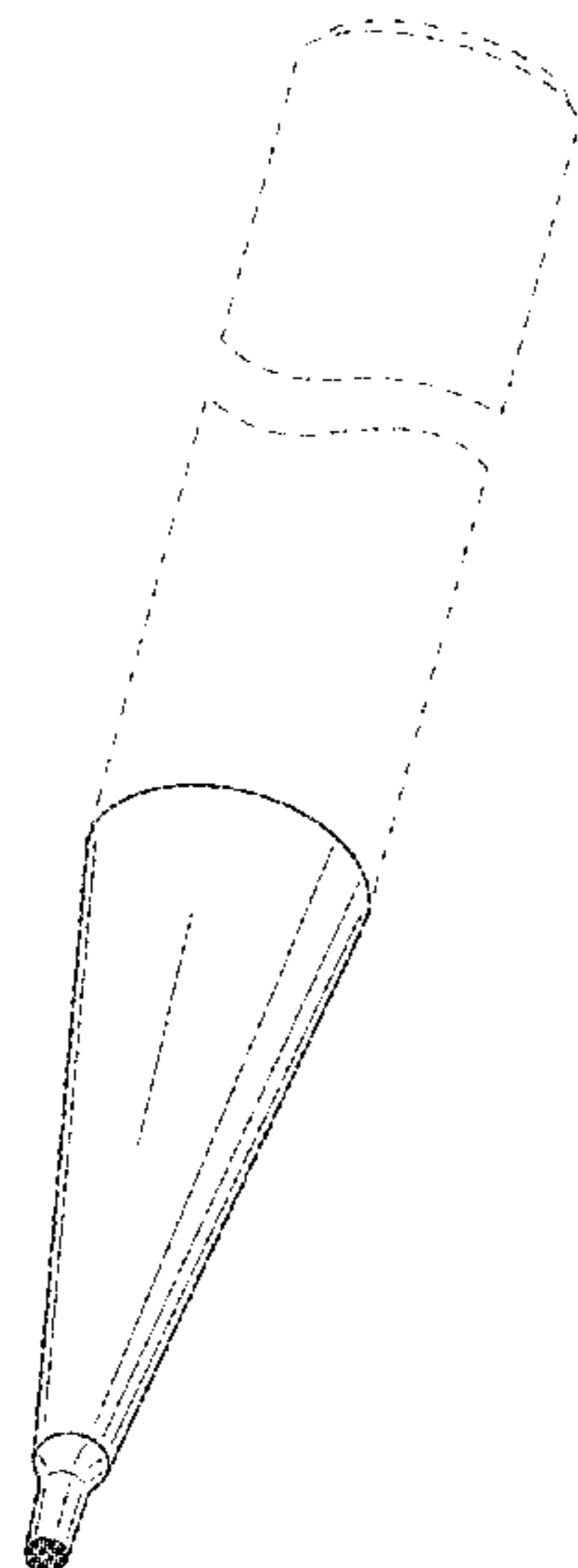
FIG. 5 depicts detailed side elevation view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 6 depicts a detailed bottom plan view of the ceramic bonding tool with textured tip shown in FIG. 4; and,

FIG. 7 depicts a detailed side cross-sectional view of the ceramic bonding tool with textured tip, the cross-section taken along cross-section indicator line 7-7 of FIG. 6.

The broken lines in the drawings illustrate environmental structure on the article and form no part of the claimed design.

1 Claim, 4 Drawing Sheets



(58) **Field of Classification Search**
 CPC .. B23K 20/004; B23K 20/005; B23K 20/106;
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 See application file for complete search history.

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 Design U.S. Appl. No. 29/516,524, filed Feb. 3, 2015, entitled Ceramic Bonding Tool with Textured Tip.

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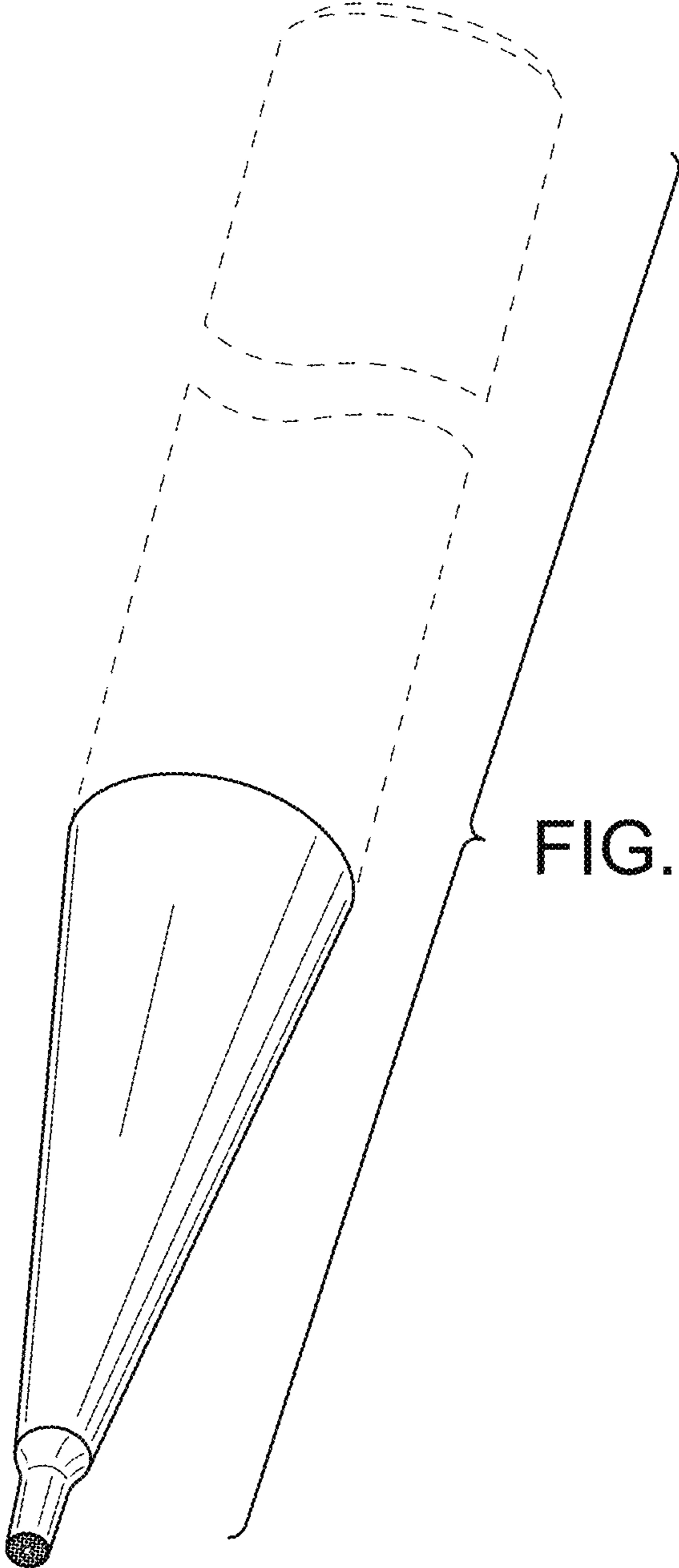


FIG. 1

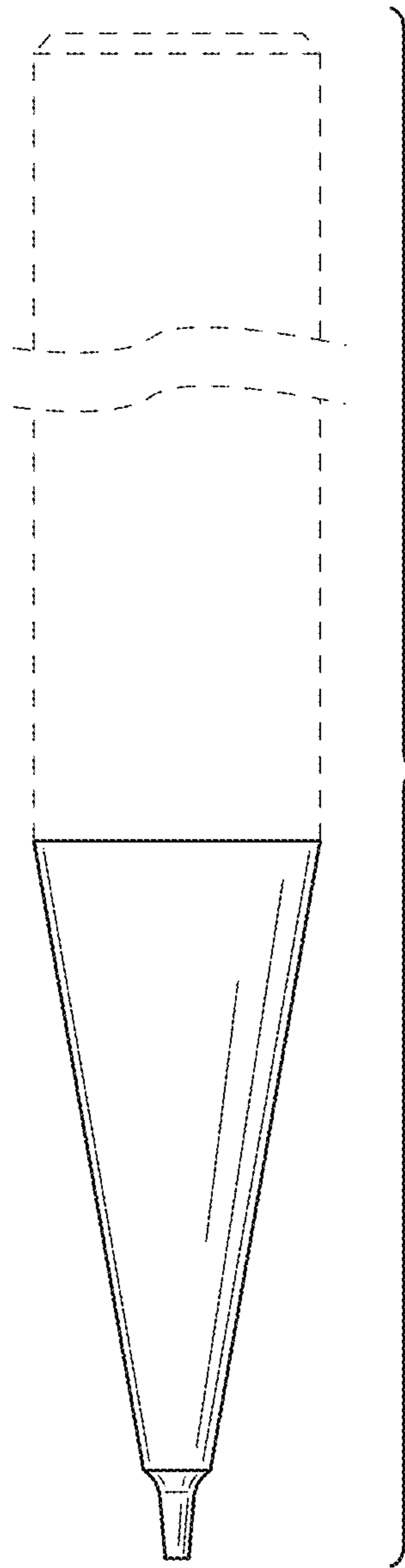


FIG. 2

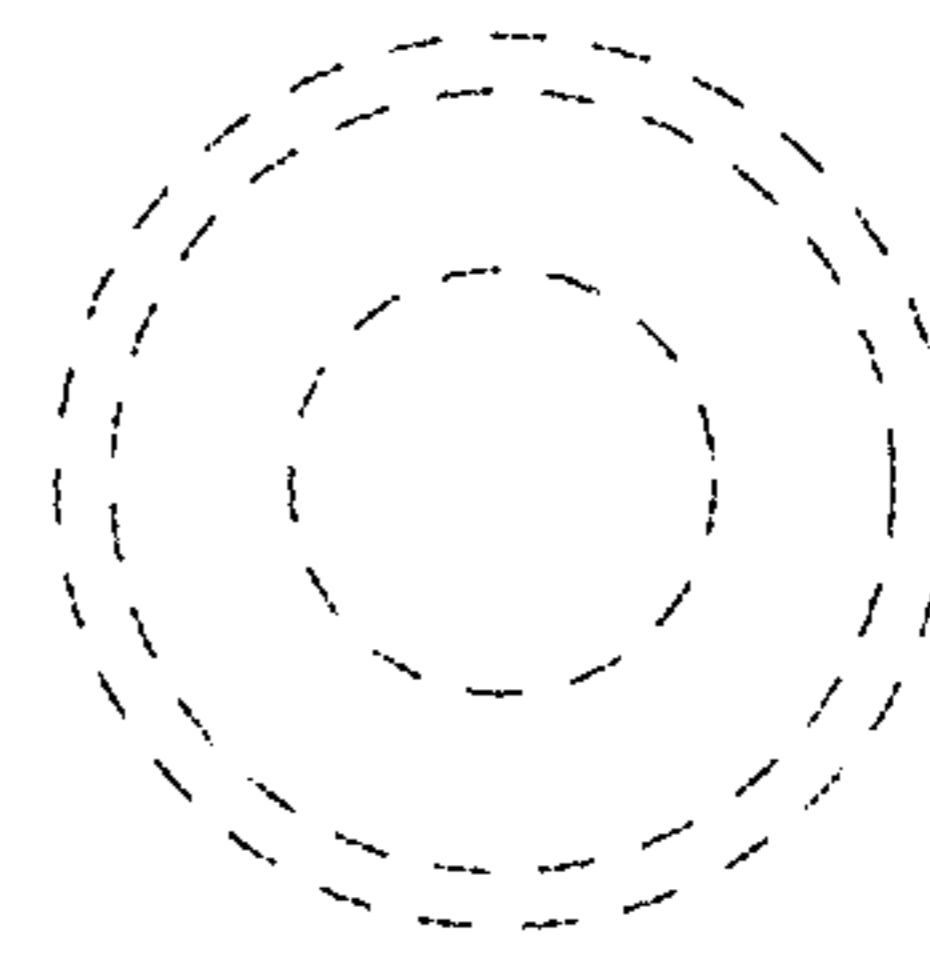


FIG. 3

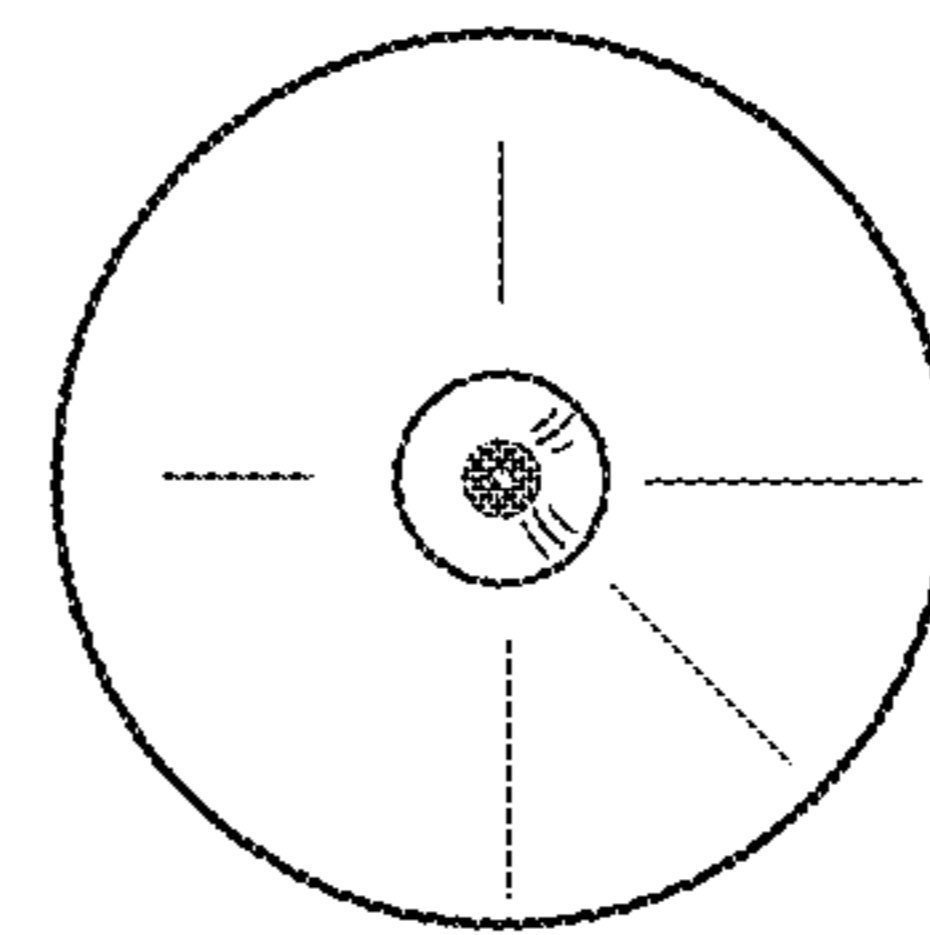


FIG. 4

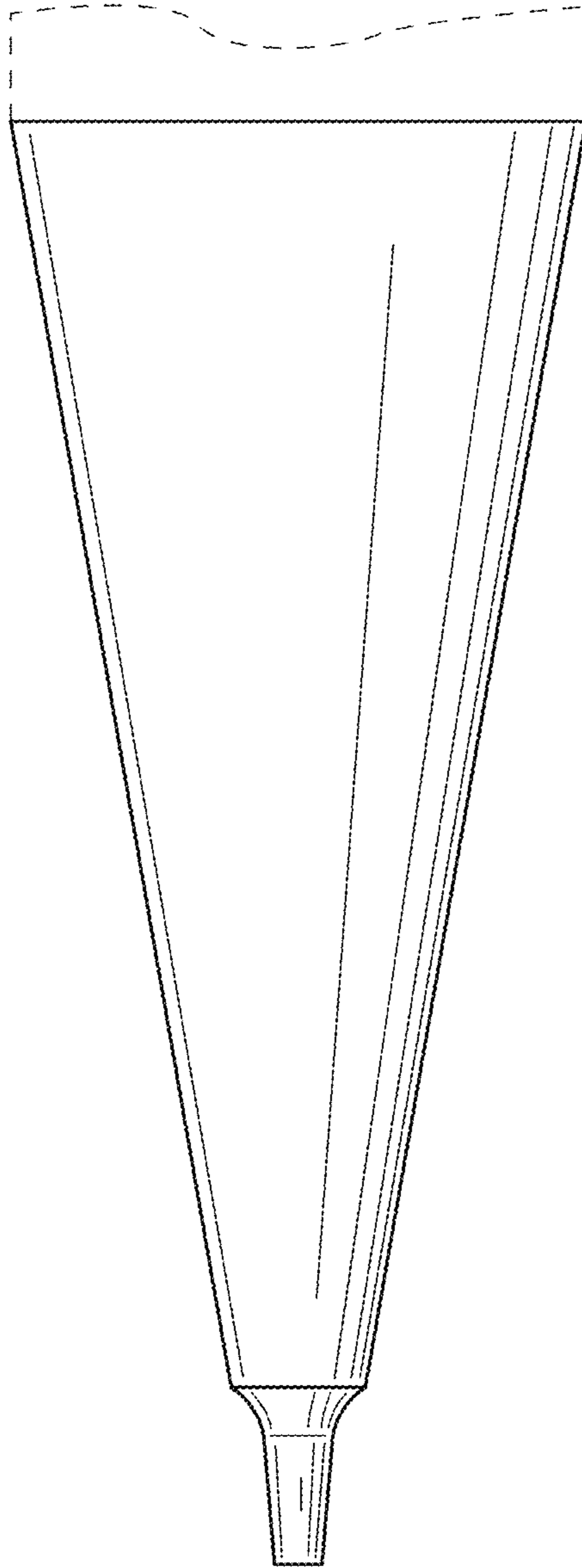


FIG. 5

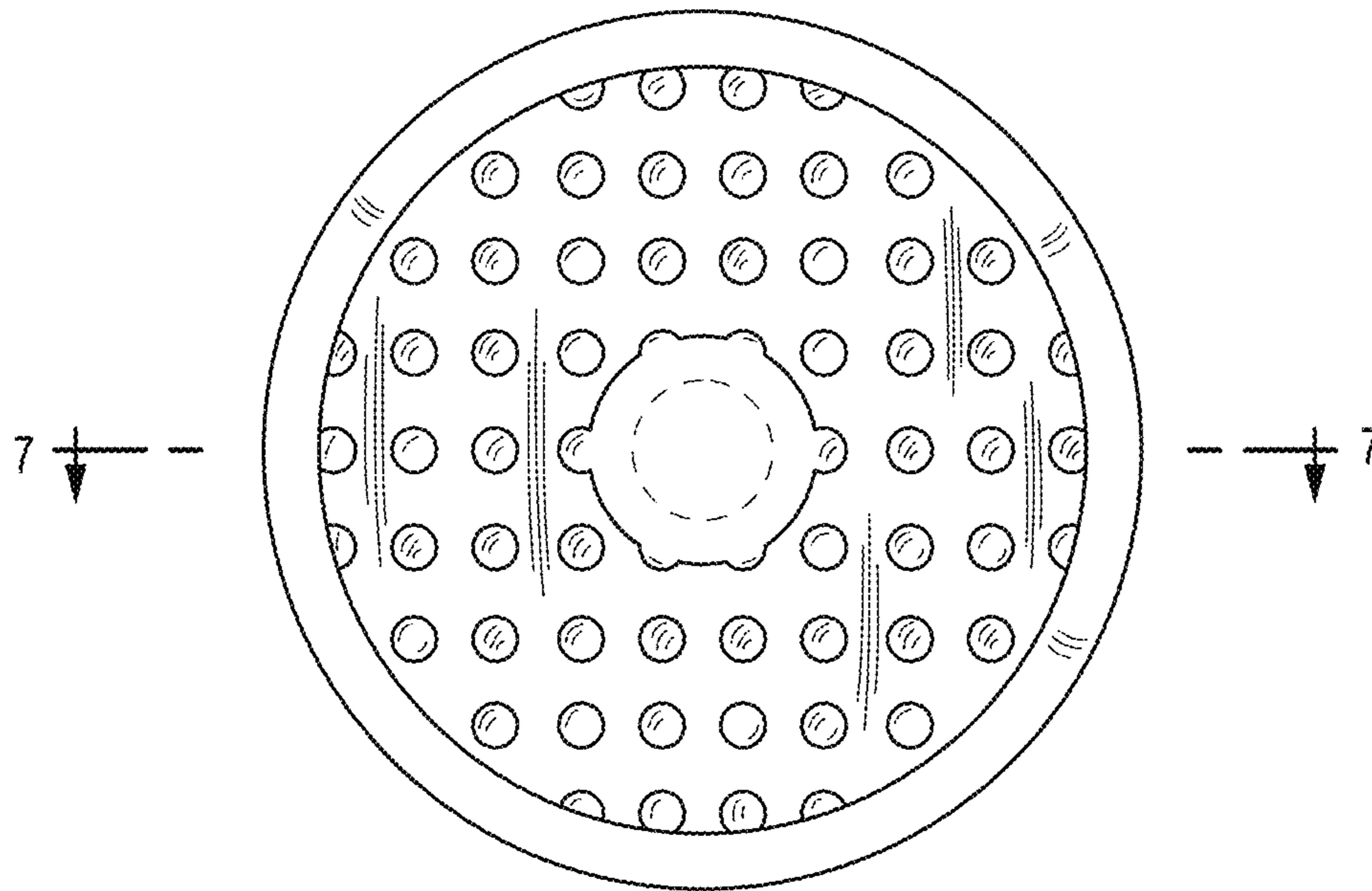


FIG. 6

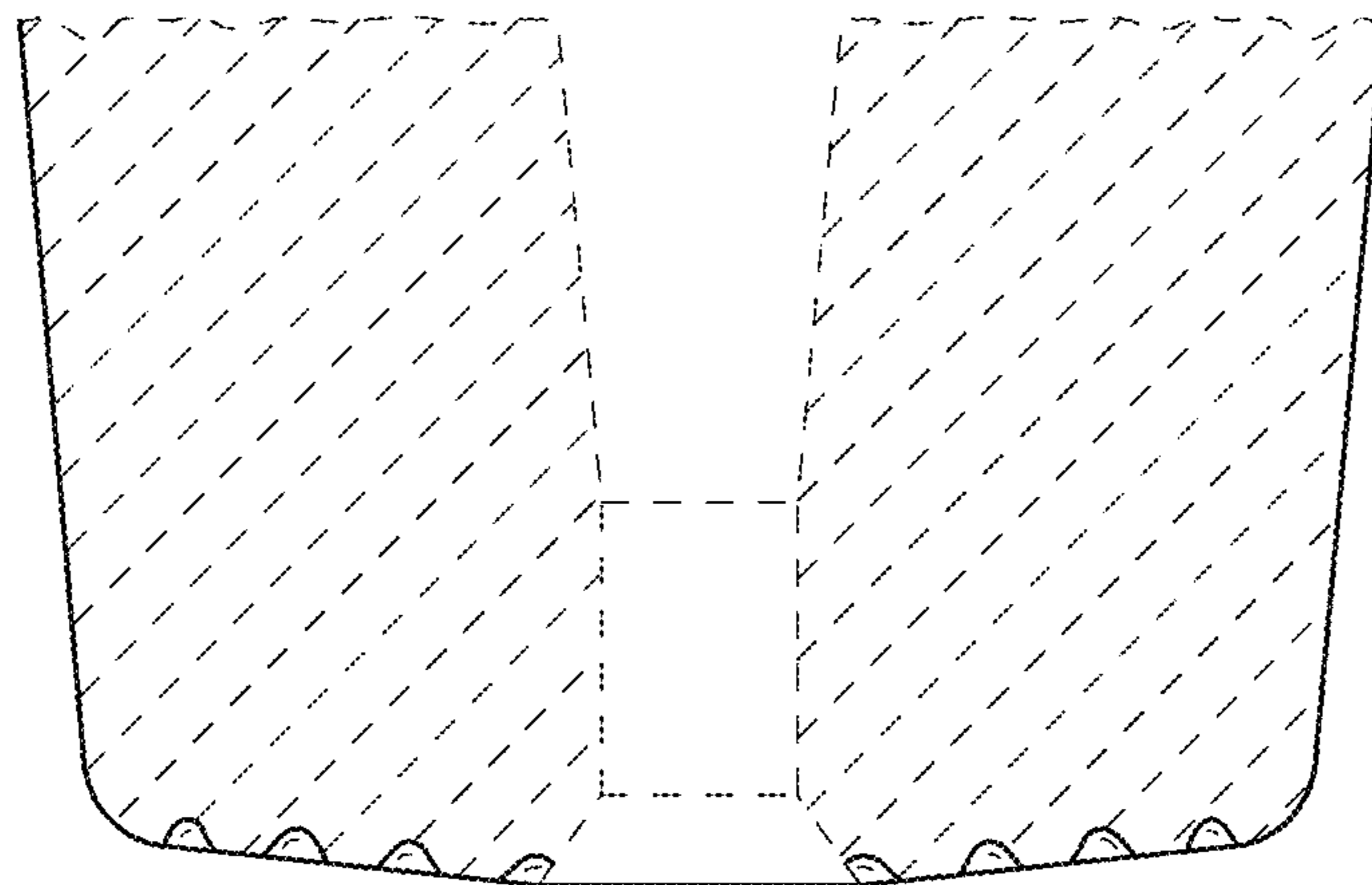


FIG. 7